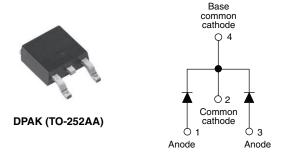


Ultrafast Rectifier, 2 x 3 A FRED Pt®



LINKS TO ADDITIONAL RESOURCES



| PRIMARY CHARACTERISTICS | | | | | | |
|----------------------------------|--------------------|--|--|--|--|--|
| I _{F(AV)} 2 x 3 A | | | | | | |
| V _R | 200 V | | | | | |
| V _F at I _F | 0.9 V | | | | | |
| t _{rr} typ. | See Recovery table | | | | | |
| T _J max. | 175 °C | | | | | |
| Package | DPAK (TO-252AA) | | | | | |
| Circuit configuration | Common cathode | | | | | |

FEATURES

- · Ultra fast recovery time
- · Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



DESCRIPTION / APPLICATIONS

Vishay Semiconductors' 200 V series are the state of the art hyper fast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyper fast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics. These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: DPAK (TO-252AA)

Molding compound meets UL 94 V-0 flammability rating **Terminals:** matte tin plated leads, solderable per

J-STD-002

| ABSOLUTE MAXIMUM RATINGS | | | | | | | |
|--|-----------------------------------|---|-------------|-------|--|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS | | | |
| Peak repetitive reverse voltage | V_{RRM} | | 200 | V | | | |
| Average rectified forward current per device | I _{F(AV)} | Total device, rated V _R , T _C = 159 °C | 6 | | | | |
| Non-repetitive peak surge current | I _{FSM} | | 50 | Α | | | |
| Peak repetitive forward current per diode | I _{FM} | Rated V _R , square wave, 20 kHz, T _C = 159 °C | 6 | | | | |
| Operating junction and storage temperatures | T _J , T _{Stg} | | -65 to +175 | °C | | | |



| ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified) | | | | | | | | |
|--|--------------------|---|------|------|------|-------|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | | |
| Breakdown voltage, blocking voltage | V_{BR} , V_{R} | $I_{R} = 100 \mu\text{A}$ | 200 | - | - | | | |
| | | I _F = 3 A | - | 0.9 | 1 | | | |
| Forward voltage | V _F | I _F = 3 A, T _J = 125 °C | - | 0.78 | 0.9 | V | | |
| Forward voltage | | I _F = 6 A | - | 1 | 1.2 | | | |
| | | I _F = 6 A, T _J = 125 °C | - | 0.89 | 1.08 | | | |
| Reverse leakage current | I _R | $V_R = V_R$ rated | - | - | 5 | | | |
| heverse leakage current | | $T_J = 125 ^{\circ}\text{C}, V_R = V_R \text{ rated}$ | | 100 | μA | | | |
| Junction capacitance | C _T | V _R = 200 V | - | 12 | - | pF | | |
| Series inductance | L _S | Measured lead to lead 5 mm from package body | - | 8.0 | - | nH | | |

| DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified) | | | | | | | | |
|---|------------------|-------------------------|--|------|------|------|-------|--|
| PARAMETER | SYMBOL | TEST | CONDITIONS | MIN. | TYP. | MAX. | UNITS | |
| | | $I_F = 1.0 A, dI_I$ | $I_F = 1.0 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$ | | 20 | 35 | | |
| Reverse recovery time | t _{rr} | T _J = 25 °C | I _F = 3 A V _R = 160 V dI _F /dt = 200 A/μs | - | 19 | - | ns | |
| | | T _J = 125 °C | | - | 26 | =. | | |
| Deals were your our went | I _{RRM} | T _J = 25 °C | | - | 3.1 | - | ^ | |
| Peak recovery current | | T _J = 125 °C | | - | 4.6 | - | A | |
| Reverse recovery charge | Q _{rr} | T _J = 25 °C | | - | 30 | - | 200 | |
| | | T _J = 125 °C | | - | 60 | - | nC | |

| THERMAL AND MECHANICAL SPECIFICATIONS | | | | | | |
|--|-----------------------------------|----------------|---------------|------------|------------------------|--|
| PARAMETER | SYMBOL | MIN. | TYP. | MAX. | UNITS | |
| Maximum junction and storage temperature range | T _J , T _{Stg} | -65 | - | 175 | °C | |
| Thermal resistance, junction to case per leg | R _{thJC} | = | - | 5 | °C/W | |
| | | - | 0.3 | - | g | |
| Weight | | - | 0.01 | - | OZ. | |
| Mounting torque | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) | |
| Marking device | | Case style DP/ | AK (TO-252AA) | 6CWH | I02FNH | |

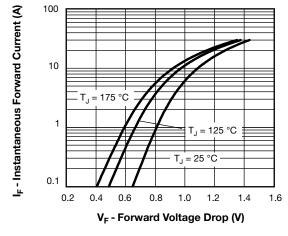


Fig. 1 - Maximum Forward Voltage Drop Characteristics

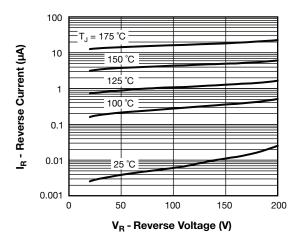


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



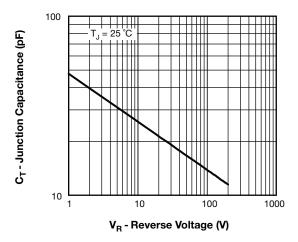


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

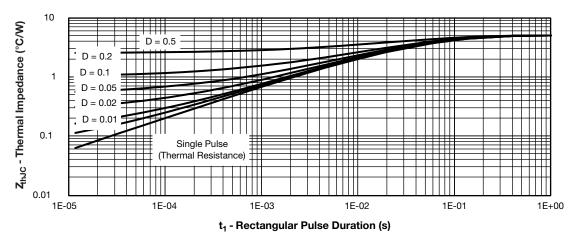


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

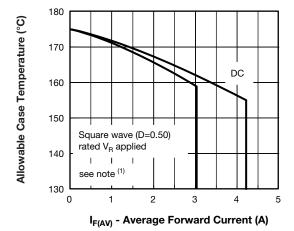
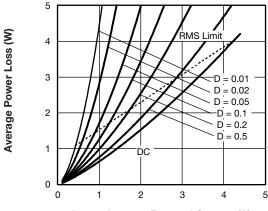


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current



I_{F(AV)} - Average Forward Current (A)

Fig. 6 - Forward Power Loss Characteristics

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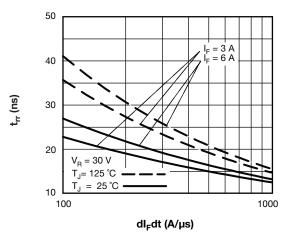


Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

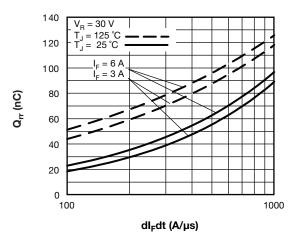


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $\begin{array}{ll} \mbox{(1)} & \mbox{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \ x \ R_{thJC}; \\ Pd = \mbox{forward power loss} = I_{F(AV)} \ x \ V_{FM} \ at \ (I_{F(AV)}/D) \ (see \ fig. \ 6); \\ Pd_{REV} = \mbox{inverse power loss} = V_{R1} \ x \ I_R \ (1 - D); \ I_R \ at \ V_{R1} = \ rated \ V_R \\ \end{array}$

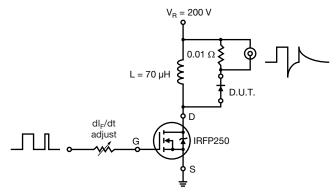
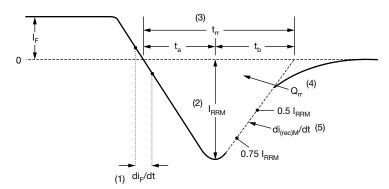


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) di_F/dt rate of change of current through zero crossing
- (2) $\rm I_{RRM}$ peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

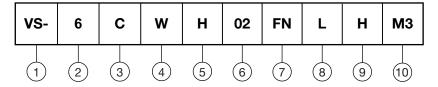
(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (6 = 6 A)

3 - Circuit configuration:

C = common cathode

Package identifier:

W = D-PAK

5 - H = hyperfast recovery

6 - Voltage rating (02 = 200 V)

7 - FN = TO-252AA

8 - L = tape and reel left oriented

If needed different orientation / packaging, please contact factory

9 - H = AEC-Q101 qualified

10 - Environmental digit:

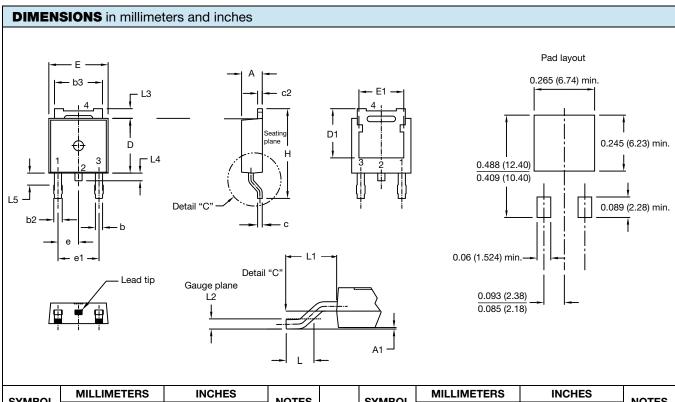
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

| ORDERING INFORMATION (Example) | | | | | | |
|---|------|-------------------|--|--|--|--|
| PREFERRED P/N BASE QUANTITY PACKAGING DESCRIPTION | | | | | | |
| VS-6CWH02FNLHM3_A | 3000 | 13" diameter reel | | | | |

| LINKS TO RELATED DOCUMENTS | | | | | |
|----------------------------|--------------------------|--|--|--|--|
| Dimensions | www.vishay.com/doc?95519 | | | | |
| Part marking information | www.vishay.com/doc?95518 | | | | |
| Packaging information | www.vishay.com/doc?95033 | | | | |



DPAK (TO-252AA)



| SYMBOL | MILLIN | IETERS | INCHES | | NOTES |
|----------|--------|--------|--------|-------|-------|
| STINIBUL | MIN. | MAX. | MIN. | MAX. | NOTES |
| Α | 2.18 | 2.39 | 0.086 | 0.094 | |
| A1 | 1 | 0.13 | - | 0.005 | |
| b | 0.64 | 0.89 | 0.025 | 0.035 | |
| b2 | 0.76 | 1.14 | 0.030 | 0.045 | |
| b3 | 4.95 | 5.46 | 0.195 | 0.215 | 3 |
| С | 0.46 | 0.61 | 0.018 | 0.024 | |
| c2 | 0.46 | 0.89 | 0.018 | 0.035 | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | 5 |
| D1 | 4.93 | - | 0.194 | - | 3 |
| Е | 6.35 | 6.73 | 0.250 | 0.265 | 5 |
| E1 | 4.32 | - | 0.170 | - | 3 |

| SYMBOL | MILLIN | IETERS | INCHES | | NOTES |
|--------|--------------------|----------|--------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | NOTES |
| е | 2.29 BSC 0.090 BSC | | | | |
| Н | 9.40 | 10.41 | 0.370 | 0.410 | |
| L | 1.40 | 1.78 | 0.055 | 0.070 | |
| L1 | 2.74 | BSC | 0.108 | REF. | |
| L2 | 0.51 | 0.51 BSC | | BSC | |
| L3 | 0.89 | 1.27 | 0.035 | 0.050 | 3 |
| L4 | - | 1.02 | - | 0.040 | |
| L5 | 1.14 | 1.52 | 0.045 | 0.060 | 2 |
| | • | • | | • | |

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (5) Outline conforms to JEDEC® outline TO-252AA, except for D1 dimension



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